<table>
<thead>
<tr>
<th>ALL ARTWORK LOCKED FROM TOP SIDE</th>
<th>BOARD NO</th>
<th>PARTS No.</th>
<th>REV. C.</th>
<th>SAFETY HAT IN HERMANN CENTER</th>
</tr>
</thead>
<tbody>
<tr>
<td>LAYER NAME = Bottom Solder</td>
<td>TID MK</td>
<td>M-A</td>
<td></td>
<td></td>
</tr>
<tr>
<td>PLOT NAME = Bottom Solder Foot</td>
<td>GENERATED</td>
<td>6-6-2017</td>
<td>12:00 PM</td>
<td>TEXAS INSTRUMENTS</td>
</tr>
</tbody>
</table>
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